

V_{DSS}	600V
$R_{DS(on)}(Max.)$	0.196Ω
I_D	±20A
P_D	68W

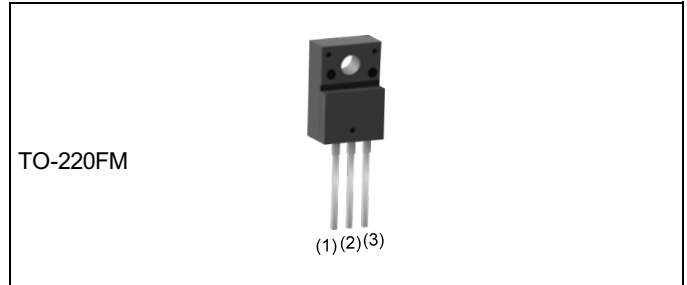
●Features

- 1) Low on-resistance
- 2) Fast switching
- 3) Drive circuits can be simple
- 4) Parallel use is easy
- 5) Pb-free plating ; RoHS compliant

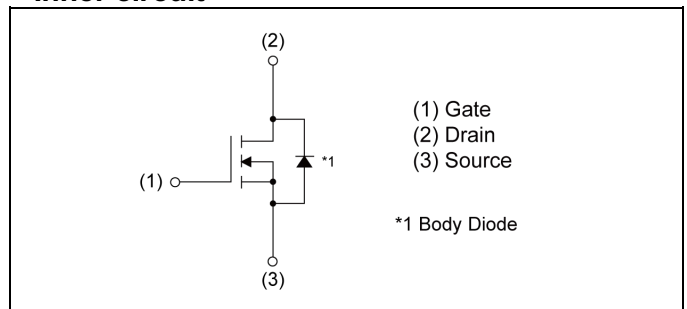
●Application

Switching

●Outline



●Inner circuit



●Packaging specifications

Code	Packing
C7 G	Tube
C7	Tube*
- (Blank)	Bulk*

*Package dimensions are different

●Absolute maximum ratings ($T_a = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V_{DSS}	600	V
Continuous drain current	I_D^{*1}	±20	A
Pulsed drain current	I_{DP}^{*2}	±60	A
Gate - Source voltage	V_{GSS}	Static	±20
		AC ($f > 1\text{Hz}$)	±30
Avalanche current, repetitive	I_{AS}	3.4	A
Avalanche energy, single pulse	E_{AS}^{*3}	418	mJ
Avalanche energy, repetitive	E_{AS}^{*3}	0.63	mJ
Power dissipation ($T_c = 25^\circ\text{C}$)	P_D	68	W
Junction temperature	T_j	150	°C
Operating junction and storage temperature range	T_{stg}	-55 to +150	°C

● **Absolute maximum ratings** ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values	Unit
Reverse diode dv/dt	dv/dt	-	15	V/ns
Drain - Source voltage slope	dv/dt	$V_{DS} = 480\text{V}, T_j = 25^\circ\text{C}$	50	V/ns

● **Thermal resistance**

Parameter	Symbol	Values			Unit
		Min.	Typ.	Max.	
Thermal resistance, junction - case	R_{thJC}	-	-	1.8	$^\circ\text{C}/\text{W}$
Thermal resistance, junction - ambient	R_{thJA}	-	-	70	$^\circ\text{C}/\text{W}$
Soldering temperature, wavesoldering for 10s	T_{sold}	-	-	265	$^\circ\text{C}$

● **Electrical characteristics** ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D = 1\text{mA}$	600	-	-	V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 600\text{V}, V_{GS} = 0\text{V}$ $T_j = 25^\circ\text{C}$	-	0.1	100	μA
		$T_j = 125^\circ\text{C}$	-	-	1000	
Gate - Source leakage current	I_{GSS}	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$	-	-	± 100	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = 10\text{V}, I_D = 1\text{mA}$	2	-	4	V
Static drain - source on - state resistance	$R_{DS(on)}^{*5}$	$V_{GS} = 10\text{V}, I_D = 9.5\text{A}$ $T_j = 25^\circ\text{C}$	-	0.170	0.196	Ω
		$T_j = 125^\circ\text{C}$	-	0.36	-	
Gate resistance	R_G	$f = 1\text{MHz}, \text{open drain}$	-	5.8	-	Ω

● Electrical characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Forward Transfer Admittance	$ Y_{fs} ^{*5}$	$V_{DS} = 10\text{V}, I_D = 10\text{A}$	5	10	-	S
Input capacitance	C_{iss}	$V_{GS} = 0\text{V}$	-	1400	-	pF
Output capacitance	C_{oss}	$V_{DS} = 25\text{V}$	-	1200	-	
Reverse transfer capacitance	C_{rss}	$f = 1\text{MHz}$	-	130	-	
Effective output capacitance, energy related	$C_{o(er)}$	$V_{GS} = 0\text{V}$	-	56	-	pF
Effective output capacitance, time related	$C_{o(tr)}$	$V_{DS} = 0\text{V to } 480\text{V}$	-	266	-	
Turn - on delay time	$t_{d(on)}^{*5}$	$V_{DD} \approx 480\text{V}, V_{GS} = 10\text{V}$	-	35	-	ns
Rise time	t_r^{*5}	$I_D = 10\text{A}$	-	53	-	
Turn - off delay time	$t_{d(off)}^{*5}$	$R_L \approx 48\Omega$	-	150	-	
Fall time	t_f^{*5}	$R_G = 10\Omega$	-	67	-	

● Gate charge characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Total gate charge	Q_g^{*5}	$V_{DD} \approx 480\text{V},$	-	60	-	nC
Gate - Source charge	Q_{gs}^{*5}	$I_D = 20\text{A},$	-	8	-	
Gate - Drain charge	Q_{gd}^{*5}	$V_{GS} = 10\text{V}$	-	33	-	
Gate plateau voltage	$V_{(plateau)}$	$V_{DD} = 480\text{V}, I_D = 20\text{A}$	-	6.9	-	V

*1 Limited only by maximum channel temperature allowed.

*2 $P_w \leq 10\mu\text{s}$, Duty cycle $\leq 1\%$

*3 $L \doteq 70\text{mH}$, $V_{DD} = 50\text{V}$, $R_G = 25\Omega$, STARTING $T_j = 25^\circ\text{C}$

*4 $T_C = 25^\circ\text{C}$

*5 Pulsed

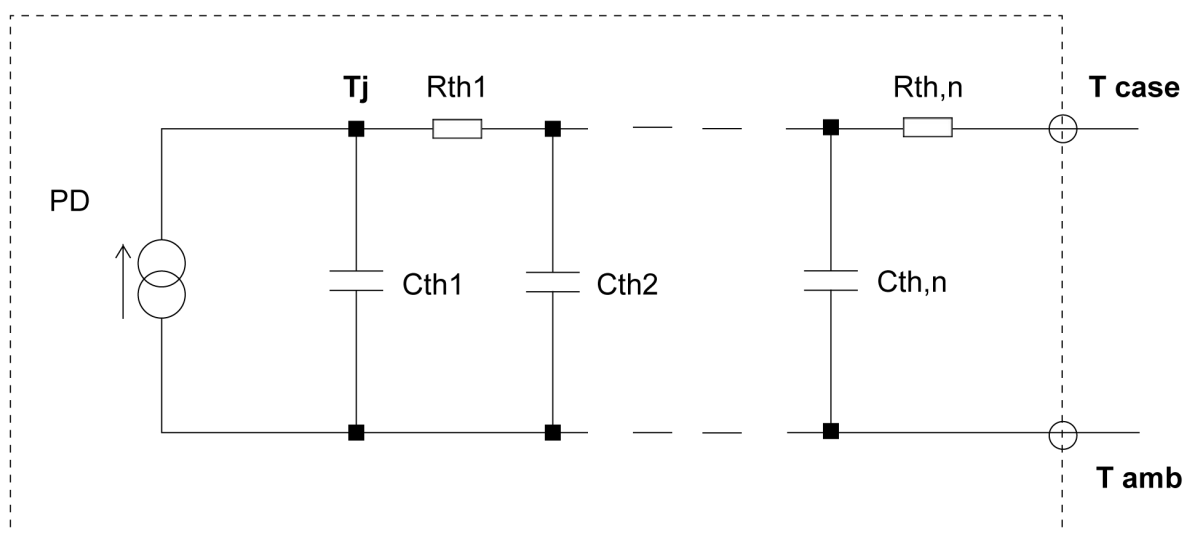
●Body diode electrical characteristics (Source-Drain) ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Continuous forward current	I_S^{*1}	$T_C = 25^\circ\text{C}$	-	-	20	A
Pulse forward current	I_{SP}^{*2}		-	-	60	A
Forward voltage	V_{SD}^{*5}	$V_{GS} = 0\text{V}, I_S = 20\text{A}$	-	-	1.5	V
Reverse recovery time	t_{rr}^{*5}	$I_S = 20\text{A}$ $di/dt = 100\text{A}/\mu\text{s}$	-	550	-	ns
Reverse recovery charge	Q_{rr}^{*5}		-	10.4	-	μC
Peak reverse recovery current	I_{rm}^{*5}		-	38	-	A

●Typical transient thermal characteristics

Symbol	Value	Unit
R_{th1}	0.118	K/W
R_{th2}	0.722	
R_{th3}	2.15	

Symbol	Value	Unit
C_{th1}	0.00216	Ws/K
C_{th2}	0.0346	
C_{th3}	0.491	



● Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

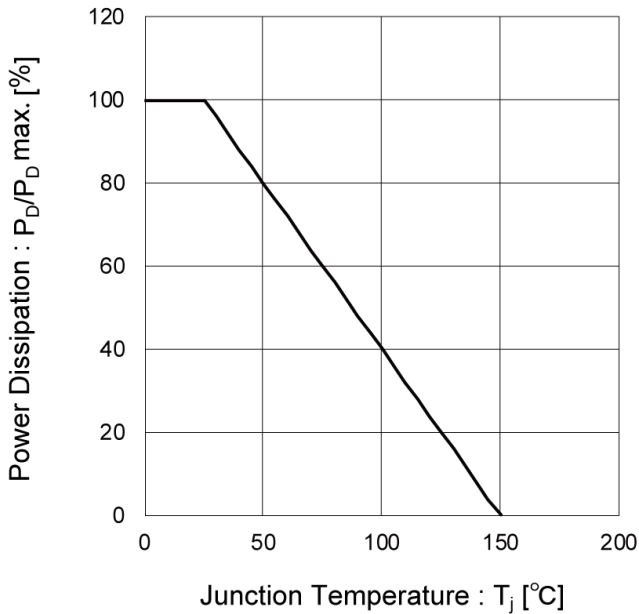


Fig.2 Drain Current Derating Curve

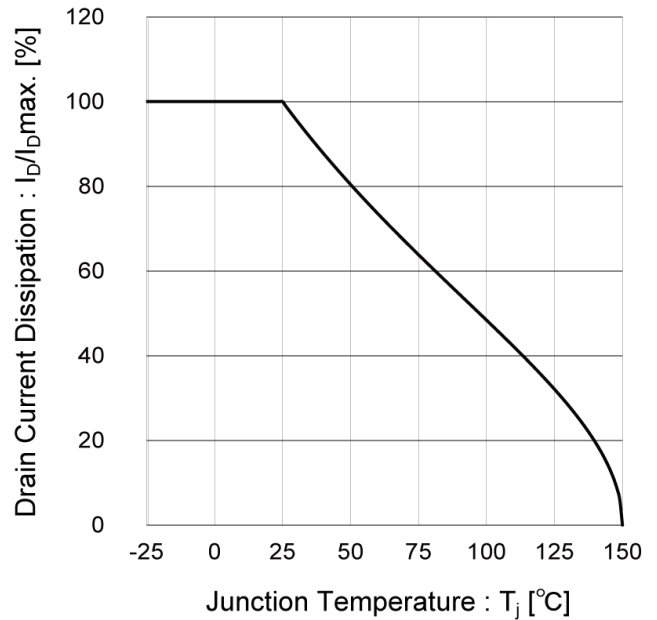


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

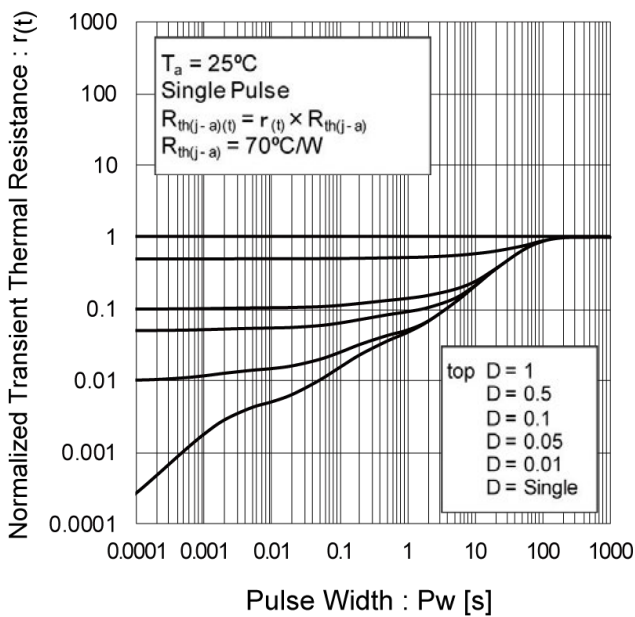
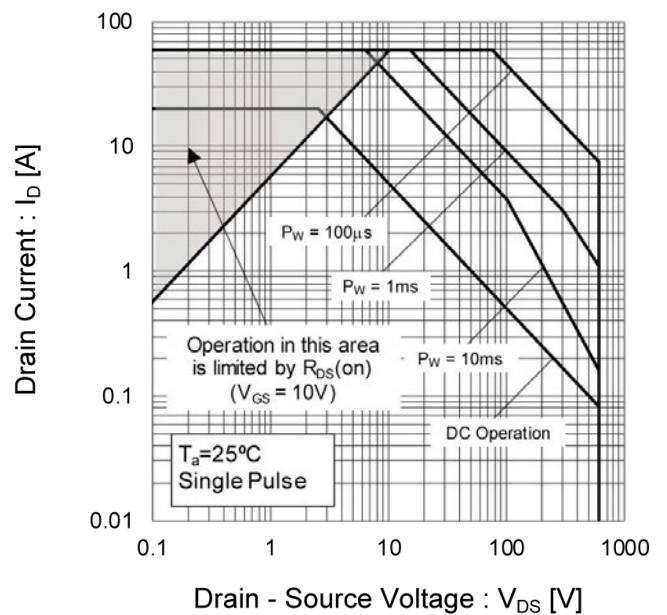


Fig.4 Maximum Safe Operating Area



● Electrical characteristic curves

Fig.5 Avalanche Energy Derating Curve

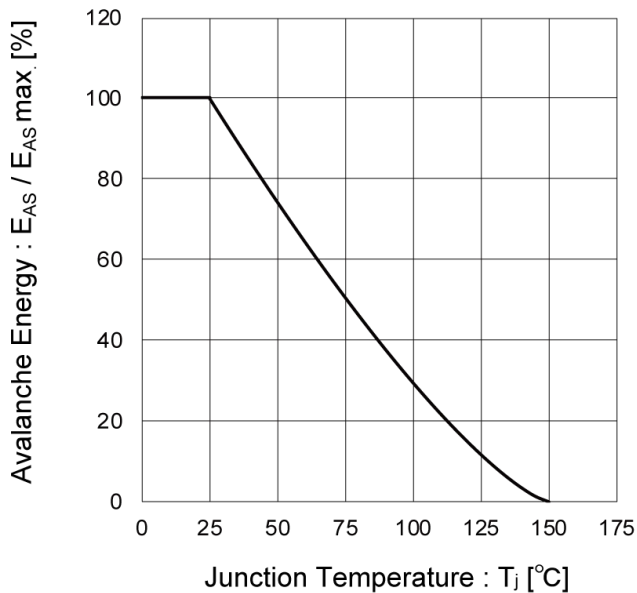


Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

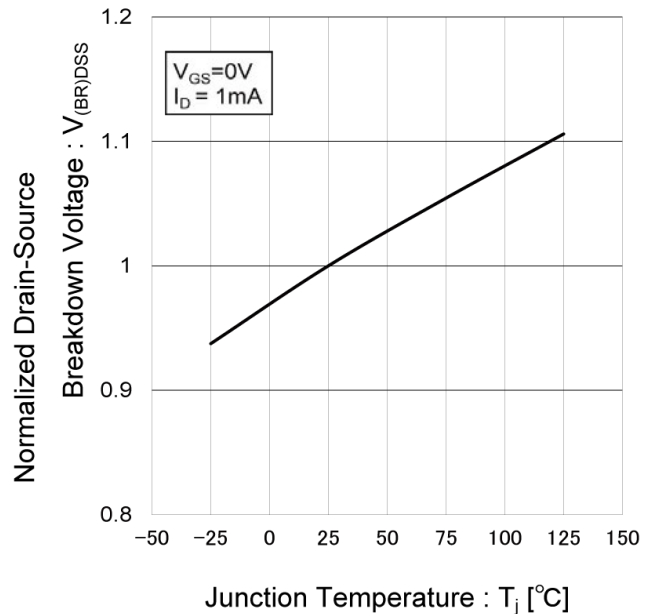


Fig.7 Typical Output Characteristics(I)

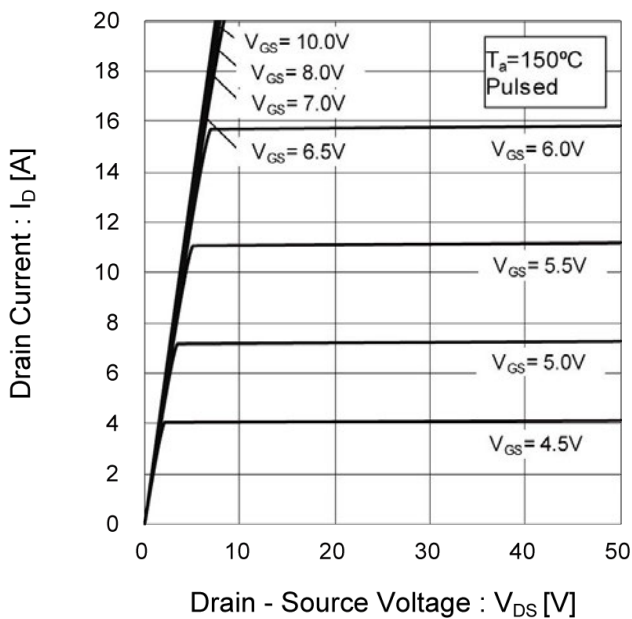
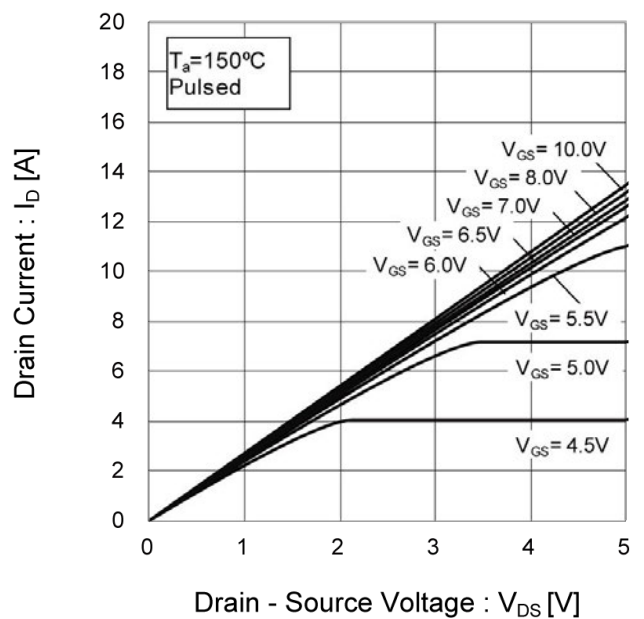


Fig.8 Typical Output Characteristics(II)



● Electrical characteristic curves

Fig.9 Typical Transfer Characteristics

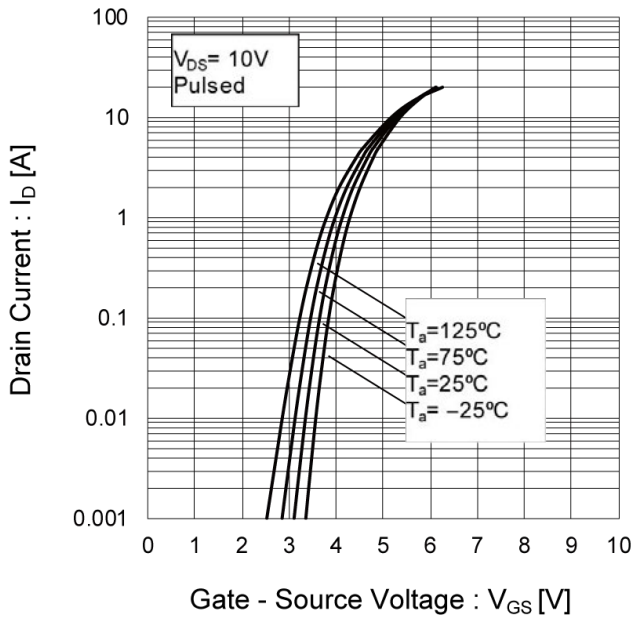


Fig.10 Gate Threshold Voltage vs. Junction Temperature

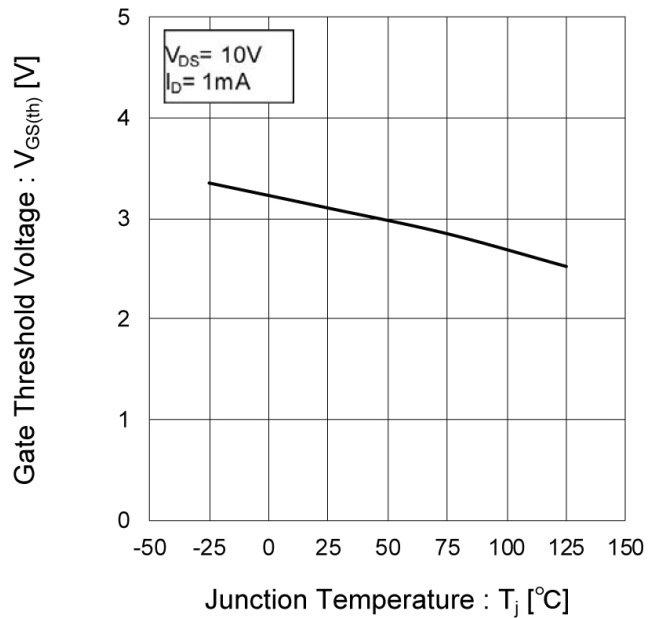


Fig.11 Static Drain - Source On - State Resistance vs. Drain Current

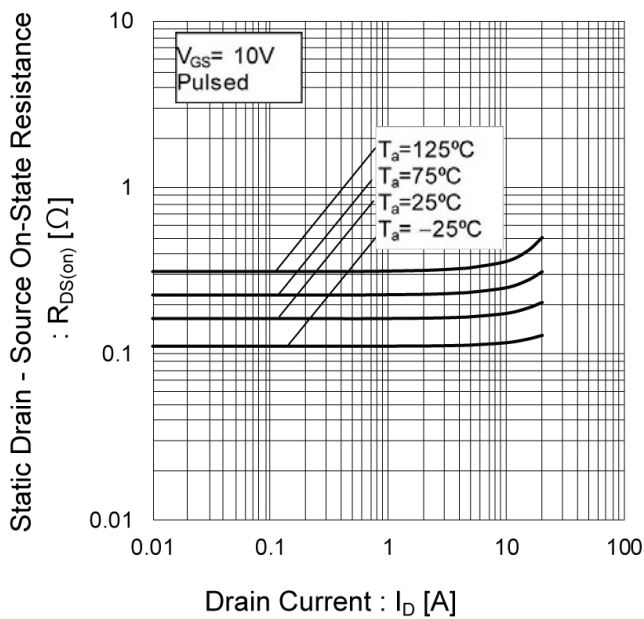
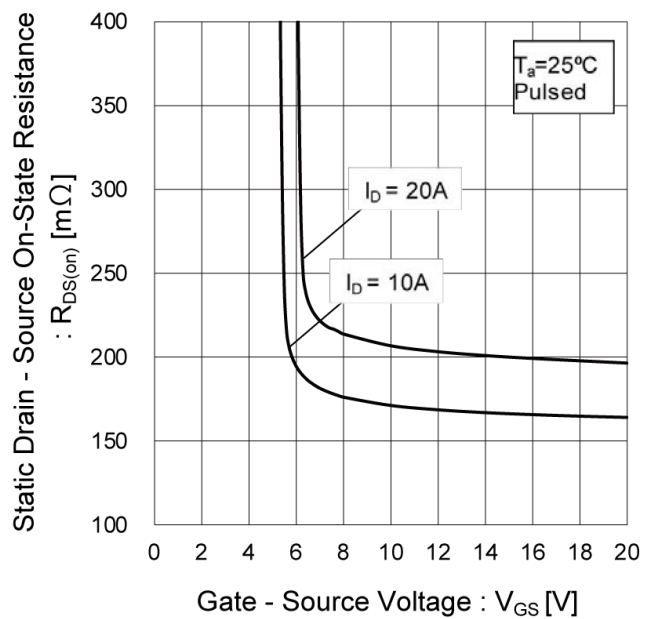


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage



● Electrical characteristic curves

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

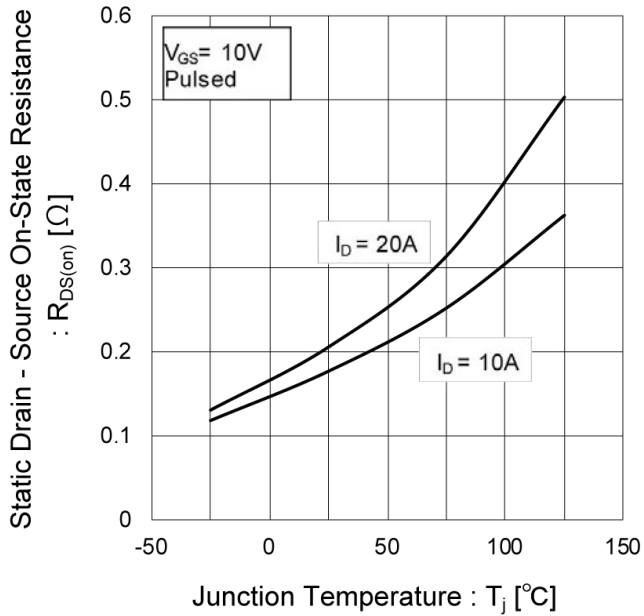


Fig.14 Typical Capacitance vs. Drain - Source Voltage

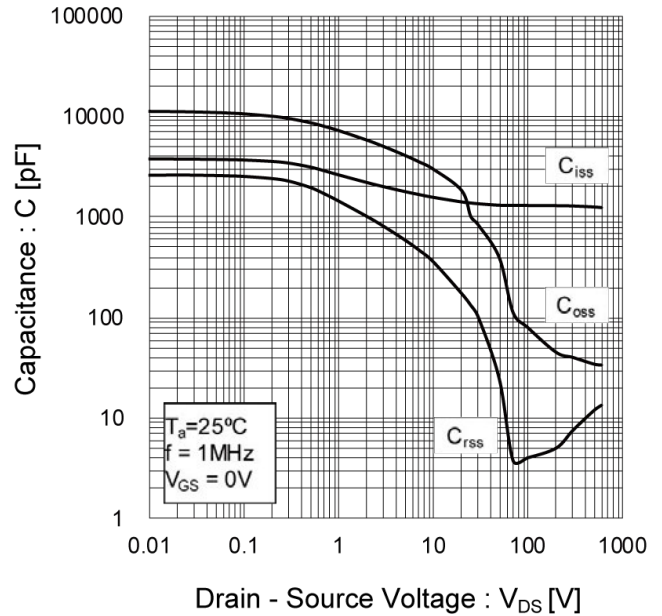


Fig.15 Switching Characteristics

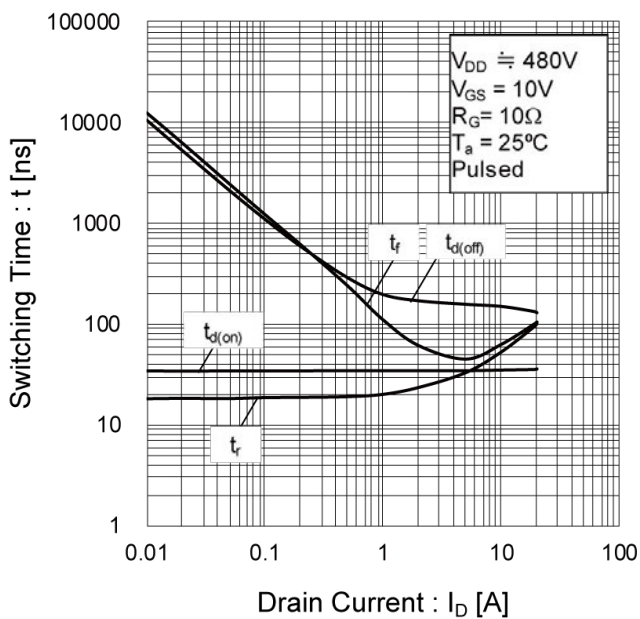
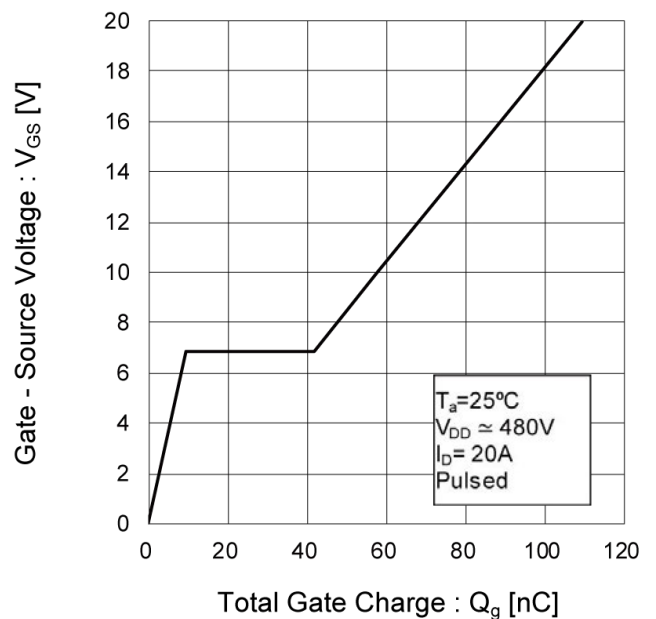


Fig.16 Typical Gate Charge



●Electrical characteristic curves

Fig.17 Source Current vs. Source - Drain Voltage

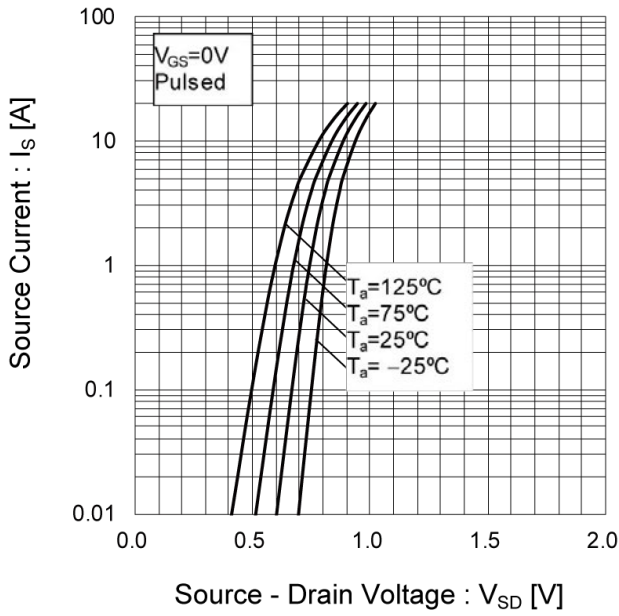
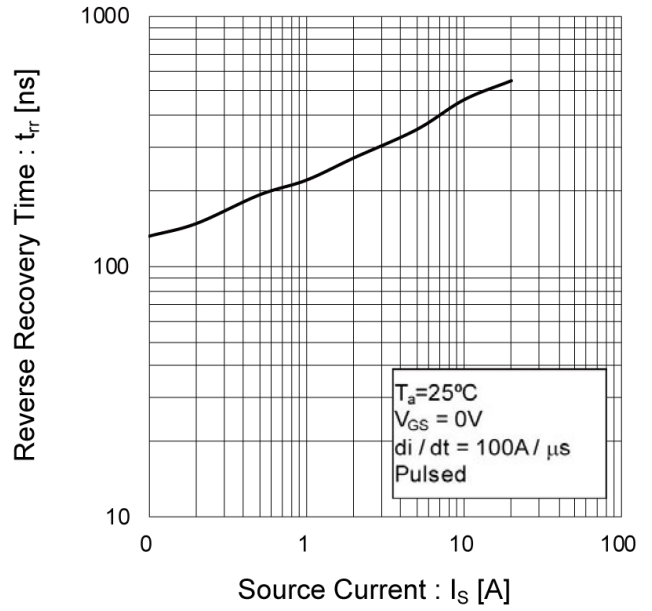


Fig.18 Reverse Recovery Time vs. Source Current



● Measurement circuits

Fig.1-1 Switching Time Measurement Circuit



Fig.1-2 Switching Waveforms



Fig.2-1 Gate Charge Measurement Circuit



Fig.2-2 Gate Charge Waveform



Fig.3-1 Avalanche Measurement Circuit



Fig.3-2 Avalanche Waveform



Fig.4-1 trr Measurement Circuit

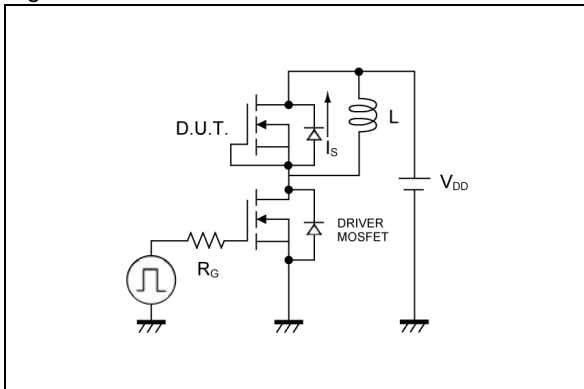
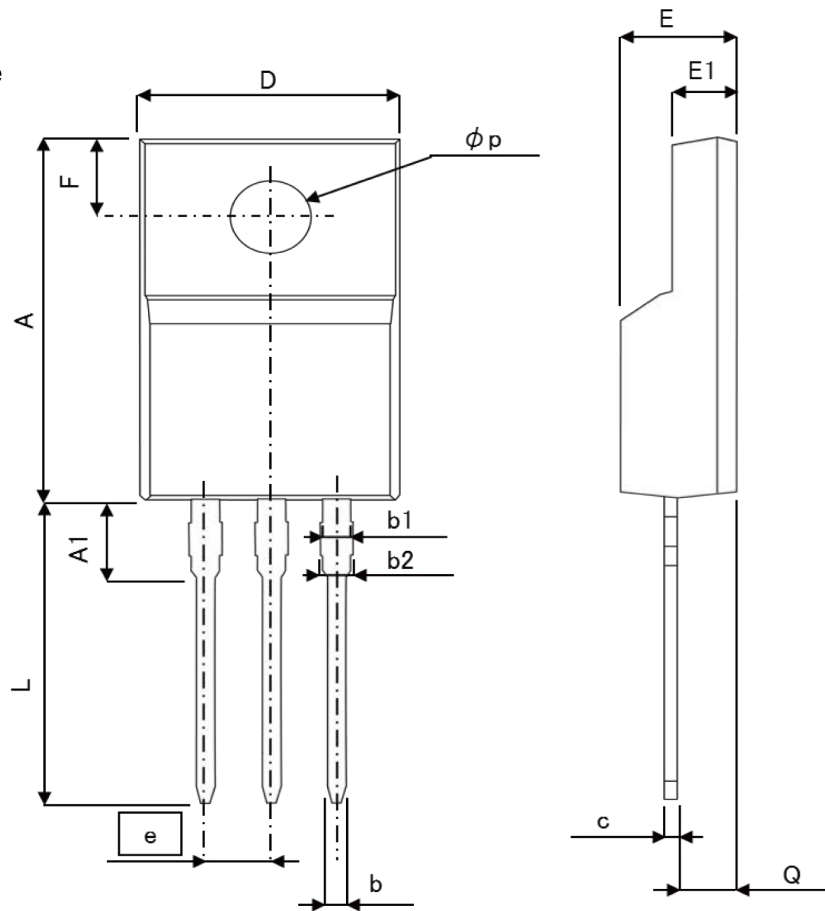


Fig.4-2 trr Waveform



●Dimensions

TO-220FM
 Packing code
 C7 G

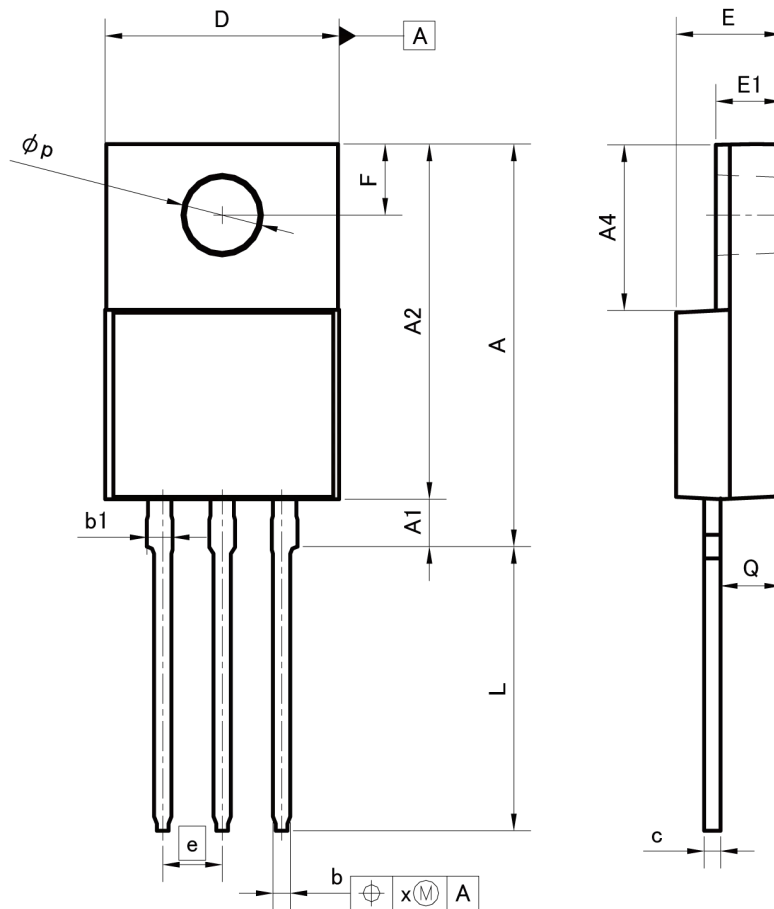


DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	15.67	16.27	0.617	0.641
A1	3.03	3.43	0.119	0.135
b	0.70	0.95	0.028	0.037
b1	1.00	1.40	0.039	0.055
b2	1.10	1.50	0.043	0.059
c	0.45	0.65	0.018	0.026
D	9.90	10.30	0.390	0.406
E	4.60	5.00	0.181	0.197
E1	2.44	2.74	0.096	0.108
e	2.54		0.100	
F	3.10	3.50	0.122	0.138
L	12.6	13.6	0.946	0.535
p	2.98	3.38	0.117	0.133
Q	2.25	3.25	0.089	0.128

Dimension in mm/inches

●Dimensions

TO-220FM
 Paking code
 C7, -(blank)



DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	16.60	17.60	0.654	0.693
A1	1.80	2.20	0.071	0.087
A2	14.80	15.40	0.583	0.606
A4	6.80	7.20	0.268	0.283
b	0.70	0.90	0.028	0.035
b1	1.10	1.50	0.043	0.059
c	0.70	0.85	0.028	0.033
D	9.90	10.30	0.390	0.406
E	4.40	4.80	0.173	0.189
e	2.54		0.100	
E1	2.70	3.00	0.106	0.118
F	2.80	3.20	0.110	0.126
L	11.50	12.50	0.453	0.492
p	3.00	3.40	0.118	0.134
Q	2.10	3.10	0.083	0.122
x	-	0.38	-	0.015

Dimension in mm/inches

Notice

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(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

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 - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
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 - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

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1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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